## **CLAIMS**

## What is claimed is:

1. A method for forming a diffractive lens, comprising:

forming a stack comprising at least two phase shifting layers separated by an etch stop layer above a first surface of a transparent substrate, the transparent substrate being transmissive to a light wavelength selected from infrared to ultraviolet; and

patterning the stack to form layers of a diffractive optical element.

- 2. The method of claim 1, wherein the transparent substrate comprises a material selected from the group consisting of quartz, Pyrex, and sapphire.
- 3. The method of claim 1, wherein said forming a stack comprises:
  - (1) depositing a first phase shifting layer comprising a material selected from the group consisting of amorphous silicon and silicon nitride;
  - (2) growing an etch stop layer comprising silicon dioxide on the first phase shifting layer; and
  - (3) depositing a second phase shifting layer comprising the material on the etch stop layer.
- 4. The method of claim 1, further comprising forming an opaque coating on a second surface of the substrate.
- 5. The method of claim 4, wherein the opaque coating comprises amorphous silicon.
- 6. The method of claim 1, further comprising, prior to said forming a stack:

  forming an antireflective coating on the first surface of the transparent substrate, wherein the stack is formed on the antireflective coating.
- 7. The method of claim 1, further comprising, subsequent to said patterning the stack: forming an antireflective coating over the diffractive optical element.
- 8. The method of claim 1, further comprising bonding a bonding ring to the first surface of the transparent substrate around the diffractive optical element.

- 9. The method of claim 8, wherein said bonding comprises forming a bond between the bonding ring and the transparent substrate selected from the group consisting of an anodic bond, an adhesive bond, a hydrofluoric acid bond, and a glass frit bond.
- 10. The method of claim 8, further comprising bonding a submount to the bonding ring to form a package.
- 11. The method of claim 1, further comprising bonding a submount to the first surface of the transparent substrate with silicone.
- 12. The method of claim 1, wherein the transparent substrate comprises a device layer of a silicon-on-insulator (SOI) substrate, the SOI substrate further comprising an insulator layer below the device layer and a handle layer below the insulator layer, the method further comprising:

etching the handle layer to the insulator layer to remove a portion of the handle layer opposite the diffractive optical element, wherein the remaining portion of the handle layer forms a bonding ring.

13. The method of claim 12, further comprising:

etching the insulator layer to remove a portion of the insulator layer opposite the diffractive optical element.

14. The method of claim 13, further comprising:

forming an antireflective coating on a second surface of the device layer opposite the diffractive optical element.

15. The method of claim 12, further comprising:

forming a bonding pad on the bonding ring.

16. The method of claim 12, further comprising:

forming a planarization layer over the diffractive optical element; and planarizing the planarization layer.

17. The method of claim 16, further comprising:

forming an antireflective layer on the planarization layer.

18. A diffractive lens, comprising:

a transparent substrate being transmissive to a light wavelength selected from infrared to ultraviolet; and

a diffractive optical element above a first surface of the transparent substrate, the diffractive optical element comprising at least two phase shifting layers separated by an etch stop layer.

- 19. The lens of claim 18, wherein the transparent substrate comprises a material selected from the group consisting of quartz, Pyrex, and sapphire.
- 20. The lens of claim 18, further comprising an opaque coating on a second surface of the substrate.
- 21. The lens of claim 20, wherein the opaque coating comprises amorphous silicon.
- 22. The lens of claim 18, further comprising:

an antireflective coating between the first surface of the transparent substrate and the diffractive optical element.

23. The lens of claim 18, further comprising:

an antireflective coating over the diffractive optical element.

24. The lens of claim 18, further comprising:

a bonding ring bonded to the first surface of the transparent substrate around the diffractive optical element.

- 25. The lens of claim 24, wherein the bonding ring is bonded to the transparent substrate by a bond selected from the group consisting of an anodic bond, an adhesive bond, a hydrofluoric acid bond, and a glass frit bond.
- 26. The lens of claim 18, further comprising:

a submount bonded to the bonding ring to form a package.

27. The lens of claim 18, further comprising:

a submount bonded to the first surface of the transparent substrate with silicone.

28. The lens of claim 18, wherein the transparent substrate comprises a device layer of a silicon-on-insulator (SOI) substrate, the SOI substrate further comprising an insulator layer

below the device layer and a handle layer below the insulator layer, the handle layer being etched so the remaining portion of the handle layer forms a bonding ring.

29. The lens of claim 28, further comprising:

an antireflective coating on a second surface of the device layer opposite the diffractive optical element.

30. The lens of claim 28, further comprising:

a bonding pad on the bonding ring.

31. The lens of claim 28, further comprising:

a planarization layer over the diffractive optical element.

32. The lens of claim 28, further comprising:

an antireflective layer over the planarization layer.

33. A method for forming a diffractive lens, comprising:

forming an etch stop layer on a first surface of a silicon substrate;

forming a diffractive optical element above the etch stop layer;

forming a planarization layer over the diffractive optical element;

planarizing the planarization layer;

bonding a transparent substrate to the planarization layer, the transparent substrate being transmissive to a light wavelength selected from infrared to ultraviolet; and

etching a second surface of the silicon substrate to the etch stop layer to remove at least a portion of the silicon substrate opposite the diffractive optical element.

- 34. The method of claim 33, wherein the transparent substrate comprises a material selected from the group consisting of quartz, Pyrex, and sapphire.
- 35. The method of claim 33, wherein said forming a diffractive optical element comprises:

forming a stack comprising at least two phase shifting layers separated by another etch stop layer above; and patterning the stack to form layers of the diffractive optical element.

36. The method of claim 33, wherein said bonding a transparent substrate to the planarization layer comprises:

forming a bonding layer on the planarization layer; and bonding the transparent substrate on the bonding layer by an anodic bond.

37. The method of claim 33, further comprising, prior to said forming a diffractive optical element:

forming an antireflective layer on the etch stop layer, wherein the diffractive optical element is formed on the antireflective layer.

38. The method of claim 37, further comprising:

etching the etch stop layer to remove a portion of the etch stop layer opposite the diffractive optical element.

- 39. The method of claim 33, wherein the remaining portion of the silicon substrate forms a bonding ring.
- 40. The method of claim 39, further comprising:

forming a bonding pad on the bonding ring.

41. The method of claim 39, further comprising:

bonding a submount to the bonding ring to form a package.

- 42. The method of claim 33, wherein said etching a second surface of the silicon substrate further comprises removing all of the silicon substrate.
- 43. A diffractive lens, comprising:

a transparent substrate being transmissive to a light wavelength selected from infrared to ultraviolet;

a planarization layer below the transparent substrate;

a diffractive optical element below the planarization layer; and an etch stop layer below the diffractive optical element.

44. The diffractive lens of claim 43, wherein the transparent substrate comprises a material selected from the group consisting of quartz, Pyrex, and sapphire.

- 45. The diffractive lens of claim 43, wherein the diffractive optical element comprises at least two phase shifting layers separated by another etch stop layer.
- 46. The diffractive lens of claim 43, further comprising:

  a bonding layer between the transparent substrate and the planarization layer.
- 47. The diffractive lens of claim 43, further comprising:

an antireflective layer between the etch stop layer and the diffractive optical element.

- 48. The diffractive lens of claim 43, further comprising:
  - a bonding ring below the etch stop layer.
- 49. The diffractive lens of claim 48, further comprising:
  - a bonding pad on the bonding ring.
- 50. The diffractive lens of claim 48, further comprising:
  - a submount bonded to the bonding ring to form a package.
- 51. A method for forming a diffractive lens, comprising:

forming a mold for a diffractive optical element on a first surface of a silicon substrate;

forming a lens layer above the mold, wherein the lens layer conforms to the mold to form the diffractive optical element, the lens layer being transmissive to a light wavelength selected from infrared to ultraviolet;

planarizing the lens layer;

bonding a transparent substrate to the lens layer; and

etching a second surface of the silicon substrate opposite of the diffractive optical element, wherein the remaining portion of the silicon substrate forms a bonding ring.

52. The method of claim 51, further comprising, prior to said forming a lens layer above the mold:

forming an etch stop layer on the mold; and

wherein the lens layer is formed on the etch stop layer and said etching a second surface of the silicon substrate comprises etching the silicon substrate to the etch stop layer.

- 53. The method of claim 51, wherein the lens layer comprises a material selected from the group consisting of silicon nitride and silicon dioxide.
- 54. The method of claim 51, wherein the transparent substrate comprises a material selected from the group consisting of quartz, Pyrex, and sapphire.
- 55. The method of claim 51, wherein said forming a mold comprises:

forming a stack comprising at least two lens layers separated by an etch stop layer; and

patterning the stack to form layers of the diffractive optical element.

56. The method of claim 51, further comprising:

forming a bonding pad on the bonding ring.

- 57. The method of claim 51, further comprising bonding a submount to the bonding ring to form a package.
- 58. A diffractive lens, comprising:

a transparent substrate being transmissive to a light wavelength selected from infrared to ultraviolet;

a diffractive optical element below the transparent substrate; and

a bonding ring below the diffractive optical element.

59. The diffractive lens of claim 58, further comprising:

an etch stop layer between the diffractive optical element and the bond ring.

- 60. The diffractive lens of claim 58, wherein the diffractive optical element comprises a material selected from the group consisting of silicon nitride and silicon dioxide.
- 61. The diffractive lens of claim 58, wherein the transparent substrate comprises a material selected from the group consisting of quartz, Pyrex, and sapphire.
- 62. The diffractive lens of claim 58, further comprising:
  - a bonding pad on the bonding ring.

63. The diffractive lens of claim 58, further comprising:

a submount bonded to the bonding ring to form a package.